

C1808X153KBGACTU

Aliases (C1808X153KBGAC7800) SMD Comm COG HV Flex, Ceramic, 0.015 uF, 10%, 630 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 1808, 2.9 mm



| General Information | |
|--------------------------|-------------------------------------|
| Series | SMD Comm COG HV Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, FT-CAP, Ultra- Stable |
| Features | FT-CAP, Ultra-Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 81 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|------------------------|
| Capacitance | 0.015 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 630 VDC |
| Dielectric Withstanding Voltage | 819 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour |
| Insulation Resistance | 66.6667 GOhms |

Click here for the 3D model.

| Dimensions | |
|------------|-----------------|
| Chip Size | 1808 |
| L | 4.7mm +/-0.5mm |
| W | 2mm +/-0.2mm |
| т | 1.6mm +/-0.15mm |
| S | 2.9mm MIN |
| В | 0.7mm +/-0.35mm |
| | |

Packaging Specifications Packaging

Packaging Quantity

T&R, 180mm, Plastic Tape 1000

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